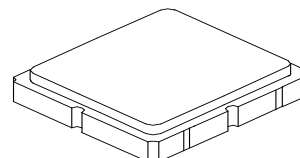


**RF1353D**

**345.00 MHz  
SAW Filter**



**SM3838-6 Case**

- *Designed for 345 MHz Low-power Wireless Applications*
- *Advanced LiTaO<sub>3</sub> Design for Low Insertion Loss*
- *Direct Match to 50 ohms*
- *Hermetically-sealed Surface Mount package*

#### Absolute Maximum Ratings

Rating	Value	Units
Maximum Input Power	+10	dBm
DC Voltage between Terminals	30	VDC
Case Temperature	-40 to +85	°C

Characteristic	Sym	Notes	Minimum	Typical	Maximum	Units
Nominal Operating Frequency	$f_C$			345		MHz
Passband Insertion Loss	IL				4.5	dB
3.0 dB Bandwidth			$f_C \pm 70$	$f_C \pm 430$	$f_C \pm 1100$	kHz
Rejection:						dB
$f_C - 10.7$ MHz			15			
$f_C - 21.4$ MHz			40			
Direct Input/Output Match:				50		$\Omega$
Operating Temperature Range			-10		70	°C
Case			SM3838-6, 3.8 x 3.8 mm Footprint			
Lid Symbolization (YY=Year, WW=week, S=shift)			444/YWWS			

#### Electrical Connections

Connection	Terminals
RF Input	2
RFOutput	5
Case Ground	All Others

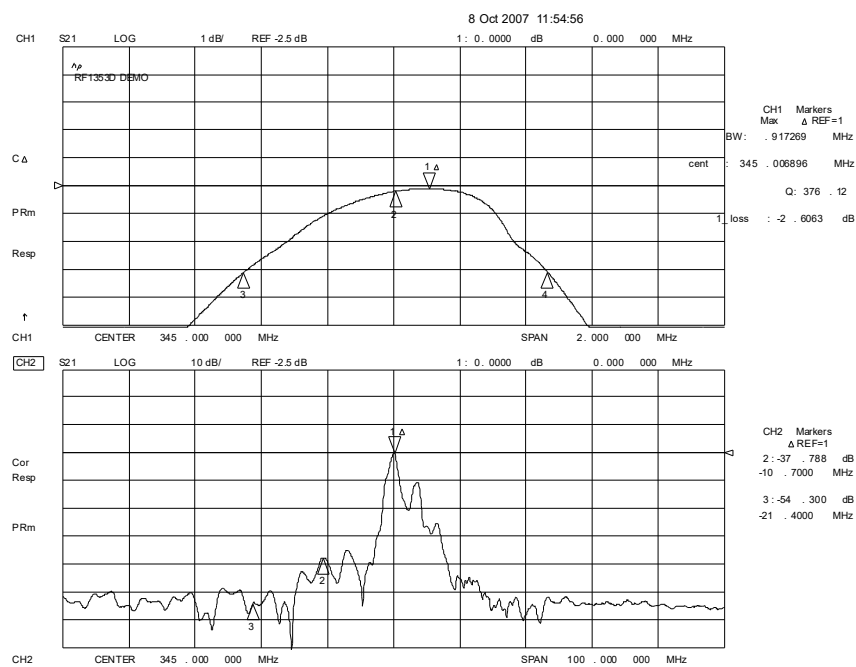


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

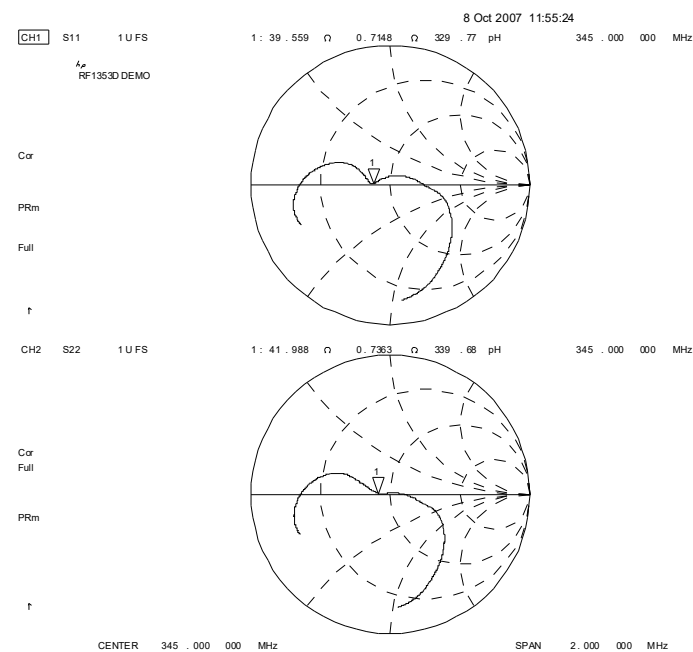
#### NOTES:

1. All specifications apply over the operating temperature range with filter soldered to the specified demonstration board unless noted otherwise.
2. Ultimate rejection is dependent on PCB layout.
3. Specifications subject to change without notice.
4. Electrostatic Sensitive Device. Observe precautions for handling.
5. US and international patents may apply.
6. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

# Filter Amplitude Response

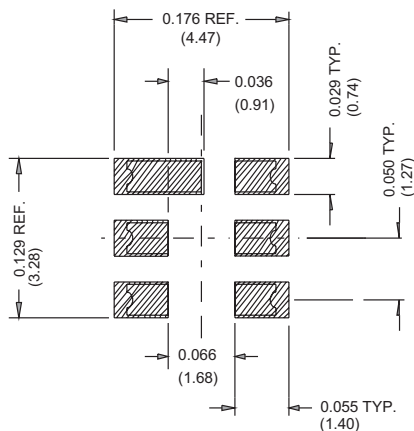
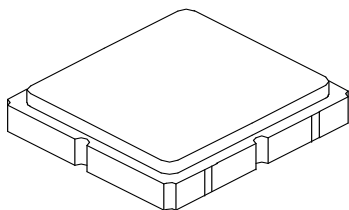


# Filter Input/Output Impedance Plots



# SM3838-6 Case

## 6-Terminal Ceramic Surface-Mount Case 3.8 X 3.8 mm Nominal Footprint



PCB Footprint

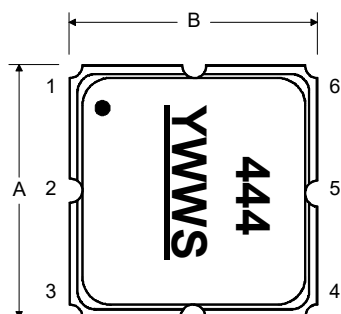
### Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.60	3.80	4.00	0.142	0.150	0.157
B	3.60	3.80	4.00	0.142	0.150	0.157
C	1.10	1.30	1.50	0.043	0.050	0.060
D	0.95	1.10	1.25	0.037	0.043	0.049
E	2.39	2.54	2.69	0.094	0.100	0.106
G	0.90	1.00	1.10	0.035	0.040	0.043
H	1.90	2.00	2.10	0.0748	0.079	0.083
I	0.50	0.60	0.70	0.020	0.024	0.028
J	1.70	1.80	1.90	0.067	0.071	0.075

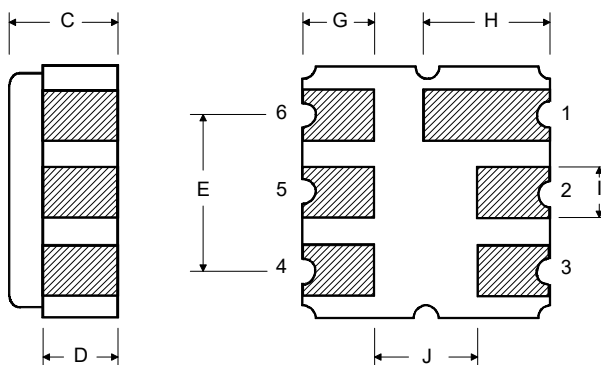
### Case Material

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu$ m Gold over 1.27 to 8.89 $\mu$ m Nickel
Lid Plating	2.0 to 3.0 $\mu$ m Nickel
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic
Pb Free	

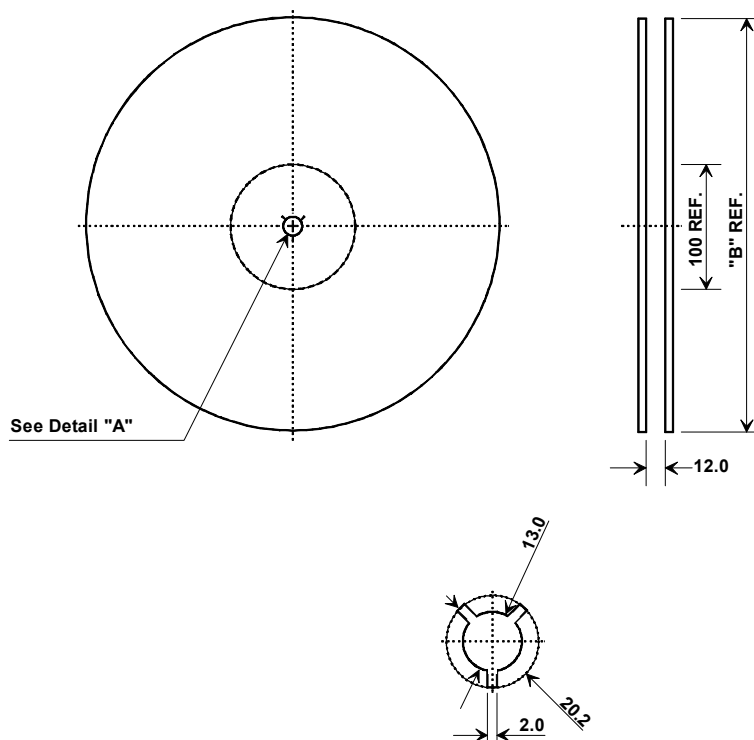
TOP VIEW



BOTTOM VIEW



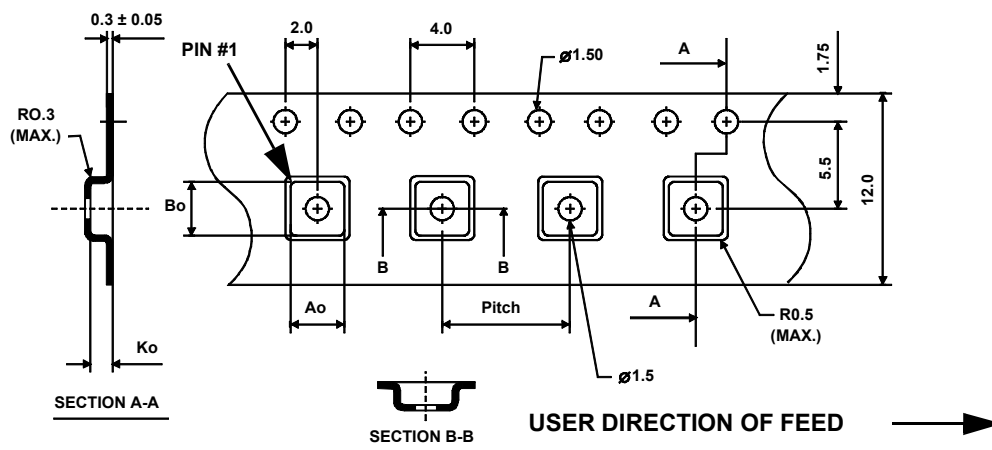
## Tape and Reel Specifications



“B” “ Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

## COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



REV	ECN NO.	DESCRIPTION	APP/DATE
A	11014	RELEASE	30sep02

D.U.T.  
(TOP VIEW)

DRAWN BY/DATE:	J.F.Christopherson 30sep02	TITLE:	ASSEMBLY DIAGRAM, RF1353D_TD (DEMO)
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		<b>A</b>	<b>2U874</b>
DWG. NO.	RF1353D-000	REV	SHEET
		A	1/2

- NOTES:
1. SOLDER MOUNT FLTR1 AND CONNECTORS TO PCB1
  2. SOLDER TAPE1 FOUR PLACES AS SHOWN.
  3. ATTACH LABELS AS SHOWN.
  4. NOTE PROPER ORIENTATION OF SAW DEVICE.
- 
- J1
- 3.
- S11
- RF1353D(DEMO)
- SN #
- RFM
- 4.
- J1
- J2
- PCB1
- S22
- 3.
- J1
- SOLDER 4X
- RFM
- TAPE1
- 2.
- J2
- |  |      |            |                 |     |       |
|--|------|------------|-----------------|-----|-------|
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|  | A    | 2U874      | NO. RF1353D-000 | A   | 2     |